

1932000-1 ✓ ACTIVE

DDR3 DIMM, DDR3 SO DIMM

TE Internal #: 1932000-1

DIMM Sockets, Double Data Rate (DDR) 3, Board-to-Board, 240

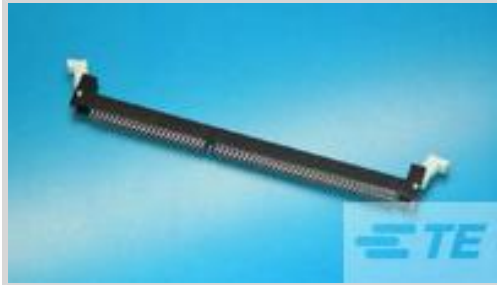
Position, Through Hole - Solder Mount, Vertical Module

Orientation, DDR3 DIMM

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DRAM Type: **Double Data Rate (DDR) 3**

Connector System: **Board-to-Board**

Number of Positions: **240**

PCB Mounting Style: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR3 DIMM Sockets \(13\)](#)

## Features

### Product Type Features

Center Post	With
DRAM Type	Double Data Rate (DDR) 3
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

### Configuration Features

Center Key	Center
Number of Keys	1
Number of Bays	2
Number of Positions	240
Module Orientation	Vertical
Keying	Standard
Number of Rows	2

### Electrical Characteristics

DRAM Voltage	1.5 V
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### Body Features



Ejector Material Color	Natural
Retention Post Material	Brass
Ejector Material	High Temperature Nylon
Ejector Location	Both Ends
Latch Material	Thermoplastic
Module Key Type	Offset Left
Latch Color	Natural
Retention Post Location	Center
Ejector Type	Standard

### Contact Features

Socket Style	DIMM
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.75 A
Contact Mating Area Plating Material	Gold Flash
Contact Mating Area Plating Thickness	.08 $\mu\text{m}$ [3.14 $\mu\text{in}$ ]
Solder Tail Contact Plating Thickness	3 $\mu\text{m}$ [118.1 $\mu\text{in}$ ]
Socket Type	Memory Card

### Termination Features

Insertion Style	Direct Insert
Termination Post Length	2.67 mm[.105 in]

### Mechanical Attachment

PCB Mount Retention	With
PCB Mount Retention Type	Retention Clip/Post
PCB Mounting Style	Through Hole - Solder
Connector Mounting Type	Board Mount
Boardlock Material	Brass
Mounting Angle	Vertical

### Housing Features

Centerline (Pitch)	1 mm[.039 in]
Housing Material	High Temperature Nylon



Housing Color	Natural
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### Dimensions

Center Retention Hole Diameter	1.8 mm[.07 in]
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Profile Height from PCB	23.1 mm[.9 in]
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Row-to-Row Spacing	1.9 mm[.075 in]
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### Usage Conditions

Operating Temperature Range	-55 – 155 °C[-67 – 311 °F]
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### Operation/Application

Circuit Application	Signal
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### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Method	Tray
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Packaging Quantity	50
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Not Yet Reviewed
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUL 2019 (201) SVHC > Threshold: Not Yet Reviewed
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Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
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Solder Process Capability	Wave solder capable to 260°C
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#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits



as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

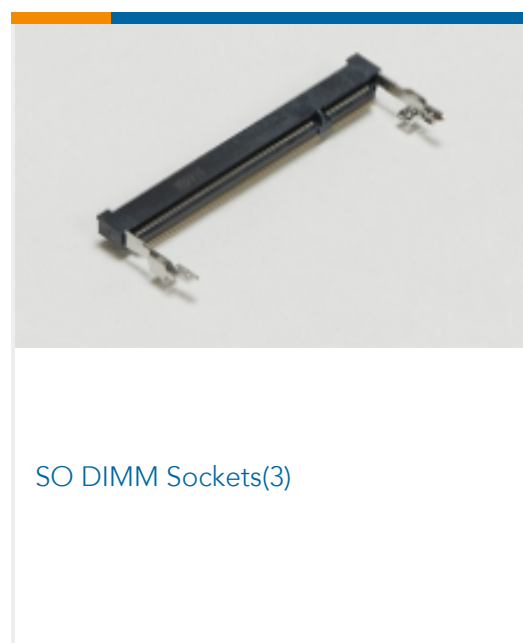
### Compatible Parts



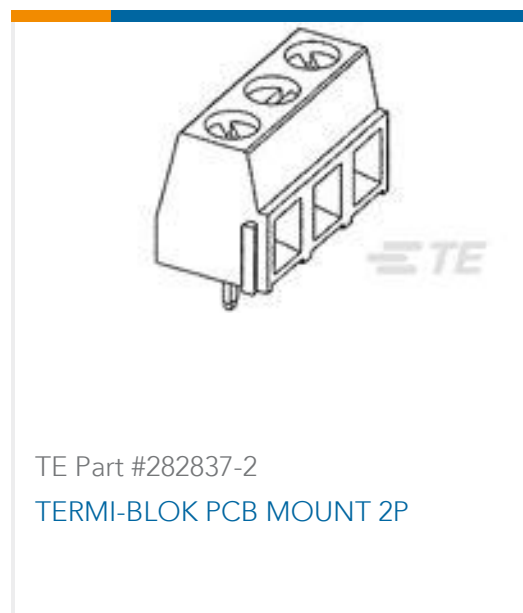
### Also in the Series | DDR3 DIMM



### Also in the Series | DDR3 SO DIMM



### Customers Also Bought





## Documents

### Product Drawings

[VERTICAL DDR3 DIMM, 240 POSITION](#)

English

### CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_1932000-1\\_F.2d\\_dxf.zip](#)

English

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1932000-1\\_F.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1932000-1\\_F.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Datasheets & Catalog Pages

[6-1773457-3\\_DDR3\\_DIMM\\_SOCKETS](#)

### Product Specifications

[Product Specification](#)

English